

### **General Description**

The MAX5102 parallel-input, voltage-output, dual 8-bit digital-to-analog converter (DAC) operates from a single +2.7V to +5.5V supply and comes in a space-saving 16-pin TSSOP package. Internal precision buffers swing Rail-to-Rail®, and the reference input range includes both ground and the positive rail. Both DACs share a common reference input.

The MAX5102 has separate input latches for each of its DACs. Data is transferred to the input latches from a common 8-bit input port. The DACs are individually selected through address input A0 and are updated by bringing WR low.

The MAX5102 features a shutdown mode that reduces current to 1nA, as well as a power-on reset mode that resets all registers to code 00 hex on power-up.

## **Applications**

Digital Gain and Offset Adjustment Programmable Attenuators Portable Instruments Power-Amp Bias Control

#### **Features**

- ♦ +2.7V to +5.5V Single-Supply Operation
- ♦ Ultra-Low Supply Current 0.2mA while Operating 1nA in Shutdown Mode
- ♦ Ultra-Small 16-Pin TSSOP Package
- ♦ Ground to VDD Reference Input Range
- ♦ Output Buffer Amplifiers Swing Rail-to-Rail
- ♦ Power-On Reset Sets All Registers to Zero

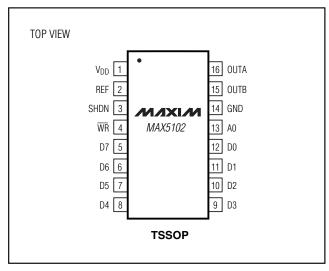
### **Ordering Information**

PART	TEMP. RANGE	PIN-PACKAGE	INL (LSB)
MAX5102AEUE	-40°C to +85°C	16 TSSOP	±1
MAX5102BEUE	-40°C to +85°C	16 TSSOP	±2

### **Functional Diagram**

## INPUT ➤ OUTA LATCH A D0-D7 INPUT ► OUTB DAC B LATCH B CONTROL ΑO MIXIM LOGIC MAX5102 REF SHDN

## **Pin Configuration**



Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd.

MIXIM

Maxim Integrated Products 1

### **ABSOLUTE MAXIMUM RATINGS**

V <sub>DD</sub> to GND	0.3V to +6V
D_, A0, WR, SHDN to GND	
REF to GND	
OUT_ to GND	0.3V to V <sub>DD</sub>
Maximum Current into Any Pin	±50mA
Continuous Power Dissipation (TA = +70	°C)
16-Pin TSSOP (derate 5.7mW/°C abo	ove $+70^{\circ}$ C) 457mW

Operating Temperature Range	
MAX5102_EUE	40°C to +85°C
Maximum Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10sec)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{DD} = V_{REF} = +2.7V \text{ to } +5.5V, \text{ GND} = 0V, \text{ R}_{L} = 10k\Omega, \text{ C}_{L} = 100pF, \text{ T}_{A} = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at  $V_{DD} = V_{REF} = +3V$  and  $T_{A} = +25^{\circ}\text{C.})$ 

PARAMETER	SYMBOL	CONE	DITIONS	MIN	TYP	MAX	UNITS	
STATIC ACCURACY	•			•				
Resolution						8	Bits	
Integral Nonlinearity (Note 1)	INL	MAX5102A	MAX5102A			±1	LSB	
integral Nonlineanty (Note 1)	IINL	MAX5102B				±2	LOD	
Differential Nonlinearity (Note 1)	DNL	Guaranteed monotoni	С			±1	LSB	
Zero-Code Error	ZCE	Code = 00 hex				±20	mV	
Zero-Code-Error Supply Rejection		Code = 00 hex, V <sub>DD</sub> =	= 2.7V to 5.5V			10	mV	
Zero-Code Temperature Coefficient		Code = 00 hex			±10		μV/°C	
Gain Error (Note 2)		Code = F0 hex				±1	%	
Gain-Error Temperature Coefficient		Code = F0 hex			±0.001		LSB/°C	
		0 1 551	V <sub>DD</sub> = 2.7V to 3.6V, V <sub>REF</sub> = 2.5V			1	1.00	
Power-Supply Rejection		Code = FF hex	V <sub>DD</sub> = 4.5V to 5.5V, V <sub>REF</sub> = 4.096V			1	LSB	
REFERENCE INPUT		I						
Input Voltage Range				0		$V_{\mathrm{DD}}$	V	
Input Resistance				320	460	600	kΩ	
Input Capacitance					15		рF	
DAC OUTPUTS								
Output Voltage Range		R <sub>L</sub> = ∞		0		$V_{REF}$	V	
DIGITAL INPUTS								
Input High Voltage	VIH	$V_{DD} = 2.7V \text{ to } 3.6V$		2			V	
	VIH	$V_{DD} = 3.6V \text{ to } 5.5V$		3			-	
Input Low Voltage	V <sub>I</sub> L					0.8	V	
Input Current	I <sub>IN</sub>	$V_{IN} = V_{DD}$ or GND				±1.0	μΑ	
Input Capacitance	CIN				10		рF	

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{DD} = V_{REF} = +2.7V \text{ to } +5.5V, \text{ GND} = 0V, \text{ R}_{L} = 10k\Omega, \text{ C}_{L} = 100pF, \text{ T}_{A} = \text{T}_{MIN} \text{ to T}_{MAX}$ , unless otherwise noted. Typical values are at  $V_{DD} = V_{REF} = +3V$  and  $T_{A} = +25^{\circ}\text{C}$ .)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DYNAMIC PERFORMANCE	'		'			
Output Voltage Slew Rate		From code 00 to code F0 hex		0.6		V/µs
Output Settling Time (Note 3)		To 1/2LSB, from code 00 to code F0 hex		6		μs
Channel-to-Channel Isolation (Note 4)		Code 00 to code FF hex		500		nVs
Digital Feedthrough (Note 5)		Code 00 to code FF hex		0.5		nVs
Digital-to-Analog Glitch Impulse		Code 80 hex to code 7F hex		90		nVs
Signal-to-Noise plus Distortion	SINAD	REF = 2.5Vp-p at 1kHz, $V_{REF(DC)}$ = 1.5V, $V_{DD}$ = 3V, code FF hex		70		
Ratio	SINAD	REF = 2.5Vp-p at 10kHz, $V_{REF(DC)}$ = 1.5V, $V_{DD}$ = 3V, code FF hex	60		- dB	
Multiplying Bandwidth		REF = 0.5Vp-p, V <sub>REF(DC)</sub> = 1.5V, V <sub>DD</sub> = 3V, -3dB bandwidth		650		kHz
Wideband Amplifier Noise				60		μV <sub>RMS</sub>
Shutdown Recovery Time	tsdr	To ±1/2LSB of final value of VOUT		13		μs
Time to Shutdown	tsdn	I <sub>DD</sub> < 5μA		20		μs
POWER SUPPLIES						
Power-Supply Voltage	V <sub>DD</sub>		2.7		5.5	V
Supply Current (Note 6)	I <sub>DD</sub>			190	360	μΑ
Shutdown Current				0.001	1	μΑ
<b>DIGITAL TIMING</b> (Figure 1) (Not	e 7)					
Address to WR Setup	tas		5			ns
Address to WR Hold	t <sub>AH</sub>		0			ns
Data to WR Setup	t <sub>DS</sub>		25			ns
Data to WR Hold	tDH		0			ns
WR Pulse Width	twR		20		ns	

- Note 1: Reduced digital code range (code 00 hex to code F0 hex) due to swing limitations when the output amplifier is loaded.
- Note 2: Gain error is: [100 (V<sub>F0,meas</sub> ZCE V<sub>F0,ideal</sub>) / V<sub>REF</sub>]. Where V<sub>F0,meas</sub> is the DAC output voltage with input code F0 hex, and V<sub>F0,ideal</sub> is the ideal DAC output voltage with input code F0 hex (i.e., V<sub>REF</sub> 240 / 256).
- Note 3: Output settling time is measured from the 50% point of the falling edge of WR to ±1/2LSB of V<sub>OUT</sub>'s final value.
- **Note 4:** Channel-to-channel isolation is defined as the glitch energy at a DAC output in response to a full-scale step change on any other DAC output. The measured channel has a fixed code of 80 hex.
- Note 5: Digital feedthrough is defined as the glitch energy at any DAC output in response to a full-scale step change on all eight data inputs with WR at VDD.
- **Note 6:**  $R_L = \infty$ , digital inputs at GND or  $V_{DD}$ .
- Note 7: Timing measurement reference level is (V<sub>IH</sub> + V<sub>IL</sub>) / 2.

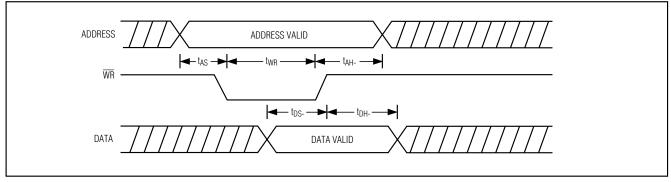
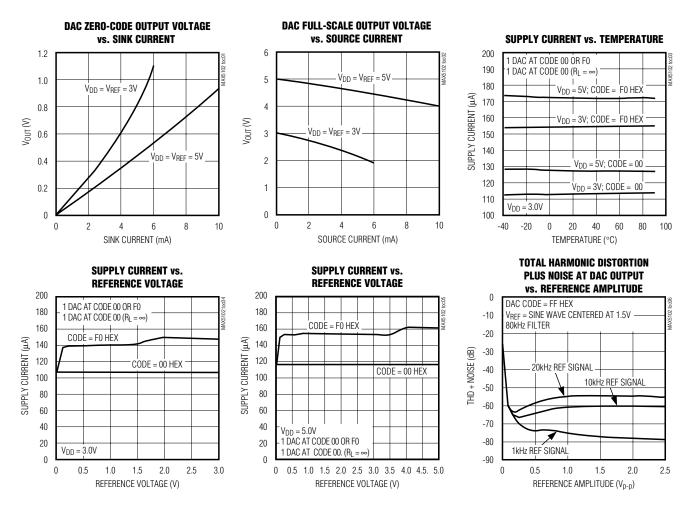


Figure 1. Timing Diagram

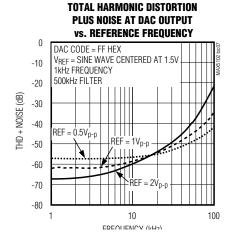
### Typical Operating Characteristics

 $(V_{DD} = V_{REF} = +3V, R_L = 10k\Omega, C_L = 100pF, code = FF hex, T_A = +25^{\circ}C, unless otherwise noted.)$ 



### **Typical Operating Characteristics (continued)**

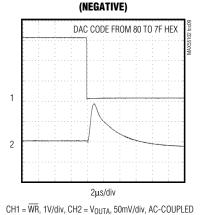
 $(V_{DD} = V_{REF} = +3V, R_L = 10k\Omega, C_L = 100pF, code = FF hex, T_A = +25^{\circ}C, unless otherwise noted.)$ 



WORST-CASE 1LSB DIGITAL STEP CHANGE (POSITIVE)

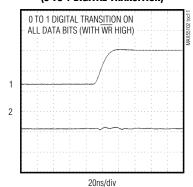
DAC CODE FROM 7F TO 80 HEX

REFERENCE INPUT FREQUENCY RESPONSE 10 0 -10 OUTPUT AMPLITUDE (dB) -20 -30 -40 -50 -60 -70 CODE = FF HEX REF IS IVp-p SIGNAL -80  $V_{REF} = 1.5V$ -90 0.01 FREQUENCY (MHz)

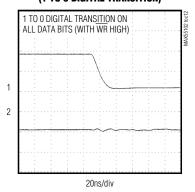


**WORST-CASE 1LSB DIGITAL STEP CHANGE** 





DIGITAL FEEDTHROUGH GLITCH IMPULSE (1 TO 0 DIGITAL TRANSITION)



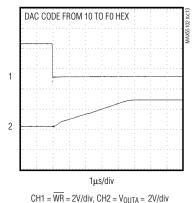
CH1 = D7, 2V/div,  $CH2 = V_{OUTA}$ , 1mV/div

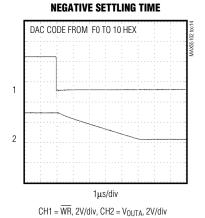


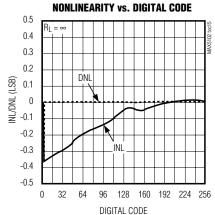


1µs/div

 $CH1 = \overline{WR}$ , 1V/div,  $CH2 = V_{OUTA}$ , 50mV/div, AC-COUPLED







2

### **Pin Description**

PIN	NAME	FUNCTION			
1	V <sub>DD</sub>	Positive Supply Voltage. Bypass V <sub>DD</sub> to GND using a 0.1µF capacitor.			
2	REF	Reference Voltage Input			
3	SHDN	Shutdown. Connect SHDN to GND for normal operation.			
4	WR	Write Input (active low). Use WR to load data into the DAC input latch selected by A0.			
5–12	D7-D0	Data Inputs			
13	A0	DAC Address Select Bit			
14	GND	D Ground			
15	OUTB	DAC B Voltage Output			
16	OUTA	DAC A Voltage Output			

### Detailed Description

### **Digital-to-Analog Section**

The MAX5102 uses a matrix decoding architecture for the DACs. The external reference voltage is divided down by a resistor string placed in a matrix fashion. Row and column decoders select the appropriate tab from the resistor string to provide the needed analog voltages. The resistor network converts the 8-bit digital input into an equivalent analog output voltage in proportion to the applied reference voltage input. The resistor string presents a code-independent input impedance to the reference and guarantees a monotonic output.

These devices can be used in multiplying applications. Their voltages are buffered by rail-to-rail op amps connected in a follower configuration to provide a rail-to-rail output (see *Functional Diagram*).

#### **Low-Power Shutdown Mode**

The MAX5102 features a shutdown mode that reduces current consumption to 1nA. A high voltage on the SHDN pin shuts down the DACs and the output amplifiers. In shutdown mode, the output amplifiers enter a high-impedance state. When bringing the device out of shutdown, allow 13µs for the output to stabilize.

#### **Output Buffer Amplifiers**

The DAC outputs are internally buffered by precision amplifiers with a typical slew rate of 0.6V/µs. The typical settling time to  $\pm 1/2$ LSB at the output is 6µs when loaded with 10k $\Omega$  in parallel with 100pF.

#### Reference Input

The MAX5102 provides a code-independent input impedance on the REF input. Input impedance is typically  $460 \mathrm{k}\Omega$  in parallel with 15pF, and the reference input voltage range is 0 to VDD. The reference input accepts positive DC signals, as well as AC signals with peak values between 0 and VDD. The voltage at REF sets the full-scale output voltage for the DAC. The output voltage (VOUT) for any DAC is represented by a digitally programmable voltage source as follows:

 $V_{OUT} = (N_B \cdot V_{REF}) / 256$ 

where N<sub>B</sub> is the numeric value of the DAC binary input code.

### Digital Inputs and Interface Logic

In the MAX5102, address line A0 selects the DAC that receives data from D0–D7, as shown in Table 1. When  $\overline{\text{WR}}$  is low, the addressed DAC's input latch is transparent. Data is latched when  $\overline{\text{WR}}$  is high. The DAC outputs (OUTA, OUTB) represent the data held in the two 8-bit

Table 1. MAX5102 Addressing Table (partial list)

WR	A0	LATCH STATE
Н	X	Input data latched
L	L	DAC A input latch transparent
L	Н	DAC B input latch transparent

H = High state, L = Low state, X = Don't care

input latches. To avoid output glitches in the MAX5102, ensure that data is valid before  $\overline{WR}$  goes low. When the device powers up (i.e.,  $V_{DD}$  ramps up), all latches are internally preset with code 00 hex.

### **Applications Information**

#### **External Reference**

The reference source resistance must be considerably less than the reference input resistance. To keep within 1LSB error in an 8-bit system, Rs must be less than RREF/256. Hence, maintain a value of Rs < 1k $\Omega$  to ensure 8-bit accuracy. If VREF is DC only, bypass REF to GND with a 0.1 $\mu$ F capacitor. Values greater than this improve noise rejection.

#### **Power Sequencing**

The voltage applied to REF should not exceed V<sub>DD</sub> at any time. If proper power sequencing is not possible,

connect an external Schottky diode between REF and  $V_{DD}$  to ensure compliance with the absolute maximum ratings. Do not apply signals to the digital inputs before the device is fully powered up.

#### Power-Supply Bypassing and Ground Management

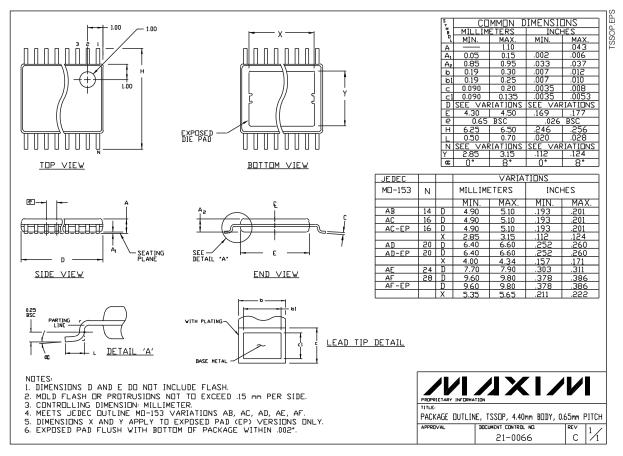
Digital or AC transient signals on GND can create noise at the analog output. Return GND to the highest-quality ground available. Bypass  $V_{DD}$  with a  $0.1\mu F$  capacitor, located as close to  $V_{DD}$  and GND as possible.

Careful PC board ground layout minimizes crosstalk between the DAC outputs and digital inputs.

\_Chip Information

TRANSISTOR COUNT: 6848

### **Package Information**



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